Advanced Design System

Advanced Design System 2020 Update 1.x Release Notes

KEYSIGHT TECHNOLOGIES

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Notices

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ADS 2020 Update 1.1 Release Notes

Release: December 20, 2019

ADS 2020 Update 1.1 (minor update release) is a cumulative minor update release installed on ADS 2020 Update 1.0 (base release). You can upgrade your existing ADS installation (ADS 2020 Update 1.0) to ADS 2020 Update 1.1 without uninstalling any previous minor updates (if available any).

Version

511.update1.1

Platform Support

- **Supported Platforms**: Windows and Linux 64-bit.

Issues Addressed

ADS 2020 Update 1.1 addresses issues related to Circuit Simulation, Data Display, Design and Technology Management, Design Editing, ElectroThermal, and EM Simulation.

Circuit Simulation

- Gcc compiler and shared library version mismatch issue can be fixed using the below workaround. **Workaround:** Set the environment as: *setenv LD_LIBRARY_PATH $HPEESOF_DIR/tiburonda/tools/linux_x86_64/lib64:$ LD_LIBRARY_PATH*
- Fixed the disruptive flow for DDR PCB Component where the component (whether pointing to an SIPro generated cell or S-data file) or the channel ID comes back as blank.

Data Display

- Improved update dataset references.
- Fixed Expression Manager refresh using multiple data-display windows.
- Improved updating expressions for Change Datasets.

Design Editing

- Fixed the Smart Mount Pcell crash where master design is null.
- Fixed the issue to now create planes partially in and partially out of a keepout, or completely out of a keepout.
- Plane 2 Plane clearance from Constraint Manager now works as expected.

Design and Tech Management

- Fixed possible library rename crash when using workspace load performance improvements.
- Fixed the "DDS File Load error" issue when using adding references to current selection.
- Fixed Archive Cell possibly selecting all libraries to archive.

ElectroThermal

- Checks the number of "independent" power sources in ETH against licensing limits.
- ETH now consumes the raw TransientVars::step_reduction_factor, without processing (clamping etc.).
- Transient and Circuit Envelope ElectroThermal simulations now aborts or exits within less than a minute.

EM Simulation

- FEM: Updated the routine that computes the mutual inductance between line segments with routines that are more stable when the segments are parallel.
- RFPro: FEM Generation 2 now correctly deals with a material where the 'resistance' specification is used.
- PIPro: Fixed an E-Field plot failure for multi-pin components.
- SIPro: Fixed the backdrill via definition issue.
- SIPro: Fixed an issue that prevented starting a simulation.

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